ATLAS ITk States Update

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ATLAS ITk Process

❖ **Wire bonding**

- solve the ASIC bond lift

- finish SS14 front-end bonding

- h0 back-end bonding

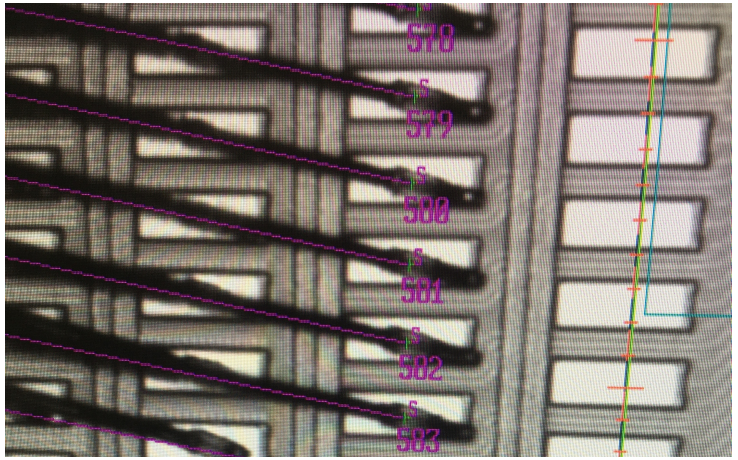
❖ Shipping test (Suyu)

- sent off the module to Dortmund (DE)

wire bonding: RAL_SS14

- ~1.5% of bonds on ABC130 lift!!
- pull test to optimize the parameters for ABC130
- solution: increase the 1st bond tail
- finish SS14 front-end bonding

50um 1st bond tail



Plan

1. Module production
   - finish hybrid wire bonding for SS15
2. Wire bonding
   - more pull test for ABC130 and hybrid
   - write a integrated program for hybrid back-end

Thank you !